146492-5 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 146492-5 PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **10**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Unshrouded

| Sealable | No |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| Stackable | Yes |
| PCB Mount Orientation | Vertical |
| Number of Positions | 10 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |
| Electrical Characteristics | |
| Insulation Resistance | 5000 MΩ |
| Body Features | |
| Primary Product Color | Black |
| Contact Features | |
| Contact Mating Area Length | 8.38 mm[.33 in] |
| Mating Square Post Dimension | .64 mm[.025 in] |

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| | 100 – 200 µin |
|--|-----------------------|
| Contact Shape & Form | Square |
| PCB Contact Termination Area Plating Material | Tin-Lead |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .381 μm[15 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 2.21 mm[.087 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |

Housing Features

| Centerline (Pitch) | 2.54 mm[.1 in] |
|--|------------------------------------|
| Housing Material | Thermoplastic |
| Dimensions | |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| Stack Height | 10.16 mm[.4 in] |
| PCB Thickness (Recommended) | 1.4 mm[.055 in] |
| Usage Conditions | |
| | |
| Operating Temperature Range | -65 – 125 °C[-85 – 257 °F] |
| Operating Temperature Range Operation/Application | -65 – 125 °C[-85 – 257 °F] |
| | -65 – 125 °C[-85 – 257 °F] None |
| Operation/Application | |
| Operation/Application Assembly Process Feature | None |
| Operation/Application Assembly Process Feature Circuit Application | None |

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Packaging Features

| Packaging Quantity | 144 |
|---|--|
| Packaging Type | Carton |
| Product Compliance For compliance documentation, visit the product page on TE.com> | |
| EU RoHS Directive 2011/65/EU | Not Compliant |
| EU ELV Directive 2000/53/EC | Compliant with Exemptions |
| China RoHS 2 Directive MIIT Order No 32, 2016 | Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) SVHC > Threshold: Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location. |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Wave solder capable to 240°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal, AMPMODU Headers



TE Part # 5-146492-5 10 MODII HDR DRST UNSHRD STKG

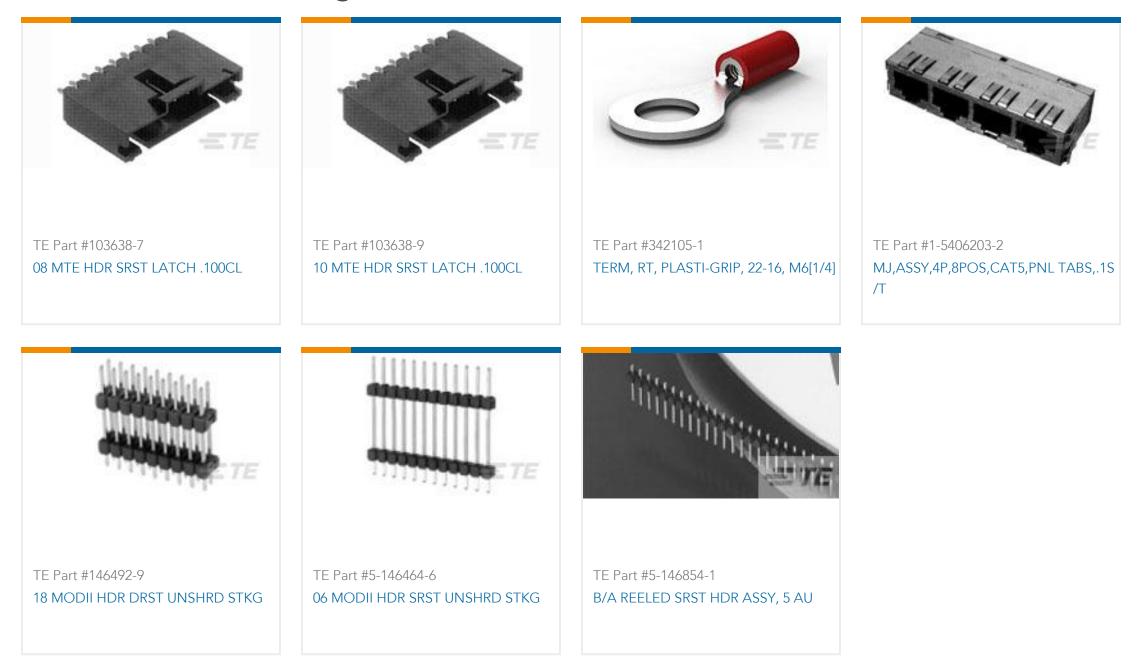
Also in the Series AMPMODU Headers





Wire-to-Board Connector Contacts(65)

Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal, AMPMODU Headers



Documents

Product Drawings 10 MODII HDR DRST UNSHRD STKG

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_146492-5_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_146492-5_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_146492-5_C.3d_stp.zip

English

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Datasheets & Catalog Pages AMPMODU Interconnetion System

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